

ABSTRACT OF DISCLOSURE

A cleaning apparatus of an electronic component of the present invention comprises: means for supplying cleaning water to an object to be cleaned such as alumina titanium carbide wafer, a sponge member for contacting with the object to be cleaned to clean a surface thereof, means for moving the object to be cleaned and the sponge member relative to each other, and means for adjusting the resistivity value of the cleaning water to $10M\Omega$ or less. Using this apparatus, the object to be cleaned is cleaned using the sponge member while supplying, to the object to be cleaned, cleaning water having the resistivity value of $10M\Omega$ or less. In this case, the cleaning degree is enhanced by soaking the object to be cleaned in the water having the resistivity value of $10M\Omega$ or less before cleaning, and by using a dummy substrate.